

# MH1M08TNA-85L,-10L,-12L,-15L/ MH1M08TNA-85H,-10H,-12H,-15H

**8388608-BIT(1048576-WORD BY 8-BIT)CMOS STATIC RAM**

**MITSUBISHI (MEMORY/ASIC)**

**DESCRIPTION**

The MH1M08TNA is a 8388608 bits CMOS static RAM module organized as 1048576-words by 8-bits. It consists of eight industry standard 128Kx8 static RAMs and one decoder.

The stand-by current is low enough for a battery back-up application. It is mounted a TSOP package on a 36-pin dual in line package.

**FEATURES**

Type	Access time (max)	Power supply current	
		Active (max)	Stand-by (max)
MH1M08TNA-85L	85ns	50mA	450μA
MH1M08TNA-10L	100ns		
MH1M08TNA-12L	120ns		
MH1M08TNA-15L	150ns		
MH1M08TNA-85H	85ns	130μA	
MH1M08TNA-10H	100ns		
MH1M08TNA-12H	120ns		
MH1M08TNA-15H	150ns		

- Single +5V Power Supply
- No Clocks, No Refresh
- Data-Hold on +2V Power Supply
- Three-State Outputs: OR-tie Capability
- Simple Memory Expansion by  $\bar{S}$
- $\bar{OE}$  Prevents Data Contention in the I/O Bus
- Common Data I/O
- 36-pin 600 mil Dual in-line package.

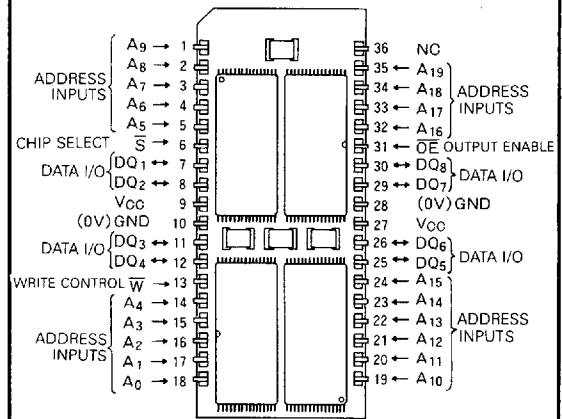
**APPLICATION**

Small Capacity Memory Units.

**FUNCTION**

The operation mode of the MH1M08TNA is determined by a combination of the device control inputs  $\bar{S}$ ,  $\bar{W}$  and  $\bar{OE}$ . Each mode is summarized in the function table. (see next page)

**PIN CONFIGURATION (TOP VIEW)**



Outline 36N1C

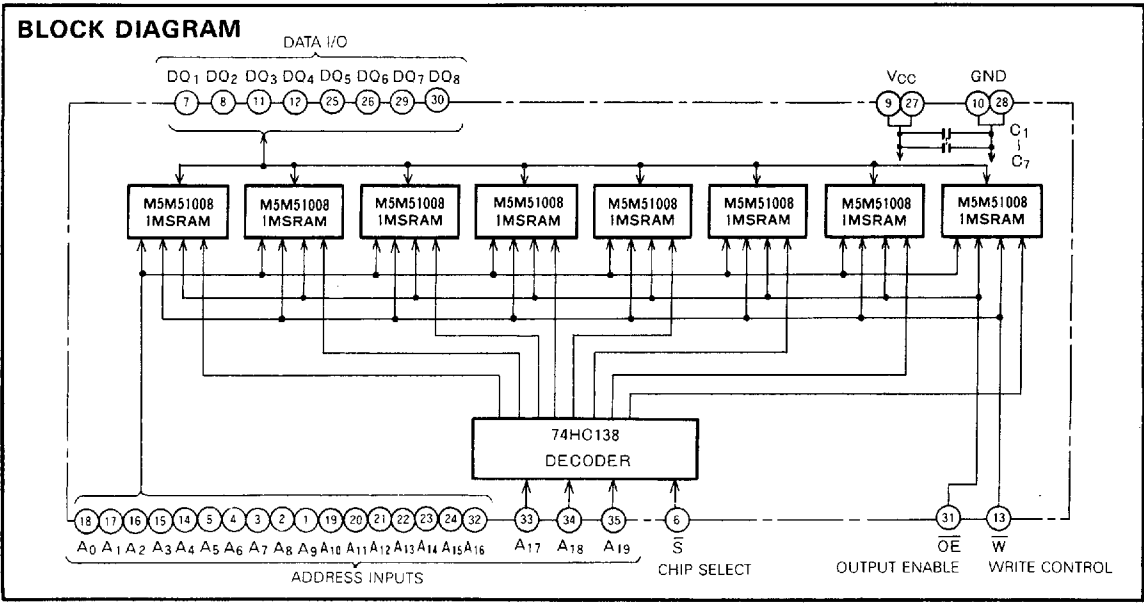
NC:NO CONNECTION

A write cycle is executed whenever the low level  $\bar{W}$  overlaps with the low level  $\bar{S}$ . The address must be set up before the write cycle and must be stable during the entire cycle. The data is latched into a cell on the trailing edge of  $\bar{W}$ ,  $\bar{S}$ , whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The output enable  $\bar{OE}$  directly controls the output stage. Setting the  $\bar{OE}$  at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.

A read cycle is executed by setting  $\bar{W}$  at a high level and  $\bar{OE}$  at a low level while  $\bar{S}$  are in an active state.

When setting  $\bar{S}$  at a high level, the chip is in a non-

**BLOCK DIAGRAM**



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selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by  $\bar{S}$ . The power supply current is reduced as low as the stand-by current which is specified as  $I_{CC3}$  or  $I_{CC4}$ , and the memory data can be held +2V power supply, enabling battery back-up operation during power failure or power-down operation in the non-selected mode.

### FUNCTION TABLE

$\bar{S}$	$\bar{W}$	$\bar{OE}$	Mode	DQ	$I_{CC}$
H	X	X	Non selection	High-impedance	Standby
L	L	X	Write	$D_{IN}$	Active
L	H	L	Read	$D_{OUT}$	Active
L	H	H		High-impedance	Active

### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
$V_{CC}$	Supply voltage	With respect to GND	-0.3 ~ 7	V
$V_I$	Input voltage		-0.3 ~ $V_{CC} + 0.3$	V
$V_O$	Output voltage		0 ~ $V_{CC}$	V
$P_d$	Power dissipation	$T_a = 25^\circ\text{C}$	700	mW
$T_{opr}$	Operating temperature		0 ~ 70	$^\circ\text{C}$
$T_{stg}$	Storage temperature		-40 ~ 100	$^\circ\text{C}$

### ELECTRICAL CHARACTERISTICS ( $T_a = 0 \sim 70^\circ\text{C}$ , $V_{CC} = 5\text{V} \pm 10\%$ , unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$V_{IH}$	High input voltage		3.2		$V_{CC} + 0.3$	V
$V_{IL}$	Low input voltage		-0.3		0.8	V
$V_{OH}$	High output voltage	$I_{OH} = -1\text{mA}$	2.4			V
$V_{OL}$	Low output voltage	$I_{OL} = 2\text{mA}$			0.4	V
$I_I$	Input current	$V_I = 0 \sim V_{CC}$			$\pm 8$	$\mu\text{A}$
$I_O$	Output current in off-state	$\bar{S} = V_{IH}$ or $\bar{OE} = V_{IH}$ , $V_{I/O} = 0 \sim V_{CC}$			$\pm 8$	$\mu\text{A}$
$I_{CC1}$	Active supply current (AC, MOS level)	$\bar{S} < 0.2$ , $\bar{W} > V_{CC} - 0.3$ output open other input $< 0.2$ or $> V_{CC} - 0.3$ Min. cycle		50	110	mA
$I_{CC2}$	Active supply current (AC, TTL level)	$\bar{S} = V_{IL}$ , $\bar{W} = V_{IH}$ output open other input $= V_{IL}$ or $V_{IH}$ Min. cycle		60	120	mA
$I_{CC3}$	Stand-by supply current	$\bar{S} \geq V_{CC} - 0.2\text{V}$ , $A_{15} \sim A_{19}$ $\leq 0.2$ or $\geq V_{CC} - 0.2$ Other inputs $= 0 \sim V_{CC}$	TNA-L		800	$\mu\text{A}$
			TNA-H		13	
$I_{CC4}$	Stand-by supply current	$\bar{S} = V_{IH}$ , Other inputs $= 0 \sim V_{CC}$			24	mA
$C_i$	input capacitance ( $T_a = 25^\circ\text{C}$ )	$V_I = \text{GND}$ , $V_I = 25\text{mVrms}$ , $f = 1\text{MHz}$			70	pF
$C_o$	Output capacitance ( $T_a = 25^\circ\text{C}$ )	$V_O = \text{GND}$ , $V_O = 25\text{mVrms}$ , $f = 1\text{MHz}$			80	pF

Note 1: Direction for current flowing into IC is indicated as positive (no mark)

2: Typical value is  $V_{CC} = 5\text{V}$ ,  $T_a = 25^\circ\text{C}$

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SWITCHING CHARACTERISTICS (Ta=0~70°C, VCC=5V±10%, unless otherwise noted)

**Read cycle**

Symbol	Parameter	Limit												Unit
		MH1M08TNA-85L MH1M08TNA-85H			MH1M08TNA-10L MH1M08TNA-10H			MH1M08TNA-12L MH1M08TNA-12H			MH1M08TNA-15L MH1M08TNA-15H			
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t <sub>CR</sub>	Read cycle time	85			100			120			150			ns
t <sub>a(A)</sub>	Address access time			85			100			120			150	ns
t <sub>a(S)</sub>	Chip select access time			85			100			120			150	ns
t <sub>a(OE)</sub>	Output enable access time			35			45			50			60	ns
t <sub>dis(S)</sub>	Output disable time after $\overline{S}$ high			40			45			50			55	ns
t <sub>dis(OE)</sub>	Output disable time after $\overline{OE}$ high			25			30			35			40	ns
t <sub>en(S)</sub>	Output enable time after $\overline{S}$ low	5			5			5			5			ns
t <sub>en(OE)</sub>	Output enable time after $\overline{OE}$ low	5			5			5			5			ns
t <sub>v(A)</sub>	Data valid time after address change	10			10			10			10			ns

**TIMING REQUIREMENTS** (Ta=0~70°C, VCC=5V±10%, unless otherwise noted)

**Write cycle**

Symbol	Parameter	Limit												Unit
		MH1M08TNA-85L MH1M08TNA-85H			MH1M08TNA-10L MH1M08TNA-10H			MH1M08TNA-12L MH1M08TNA-12H			MH1M08TNA-15L MH1M08TNA-15H			
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t <sub>CW</sub>	Write cycle time	85			100			120			150			ns
t <sub>w(W)</sub>	Write pulse width	55			65			75			85			ns
t <sub>SU(A)</sub>	Address set up time	0			0			0			0			ns
t <sub>SU(A-<math>\overline{WH}</math>)</sub>	Address set up time with respect to $\overline{W}$ high	65			75			85			100			ns
t <sub>SU(S)</sub>	Chip select set up time	80			90			100			115			ns
t <sub>SU(D)</sub>	Data set up time	30			35			40			45			ns
t <sub>h(D)</sub>	Data hold time	0			0			0			0			ns
t <sub>rec(W)</sub>	Write recovery time	0			0			0			0			ns
t <sub>dis(W)</sub>	Output disable time after $\overline{W}$ low			25			30			35			40	ns
t <sub>dis(OE)</sub>	Output disable time after $\overline{OE}$ high			25			30			35			40	ns
t <sub>en(W)</sub>	Output enable time after $\overline{W}$ high	5			5			5			5			ns
t <sub>en(OE)</sub>	Output enable time after $\overline{OE}$ low	5			5			5			5			ns

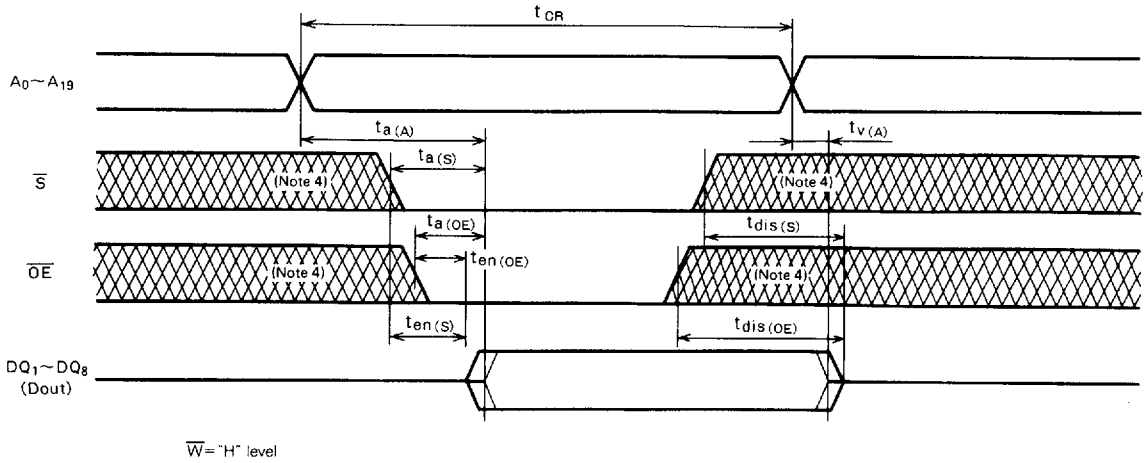
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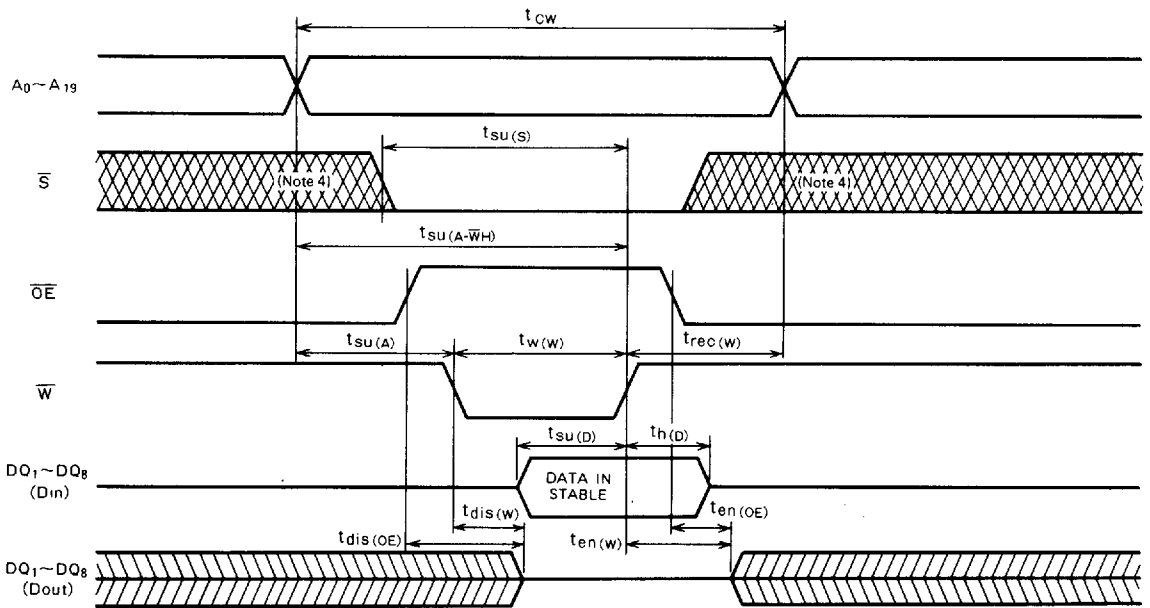
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## TIMING DIAGRAM

### Read cycle



### Write cycle ( $\bar{W}$ control)

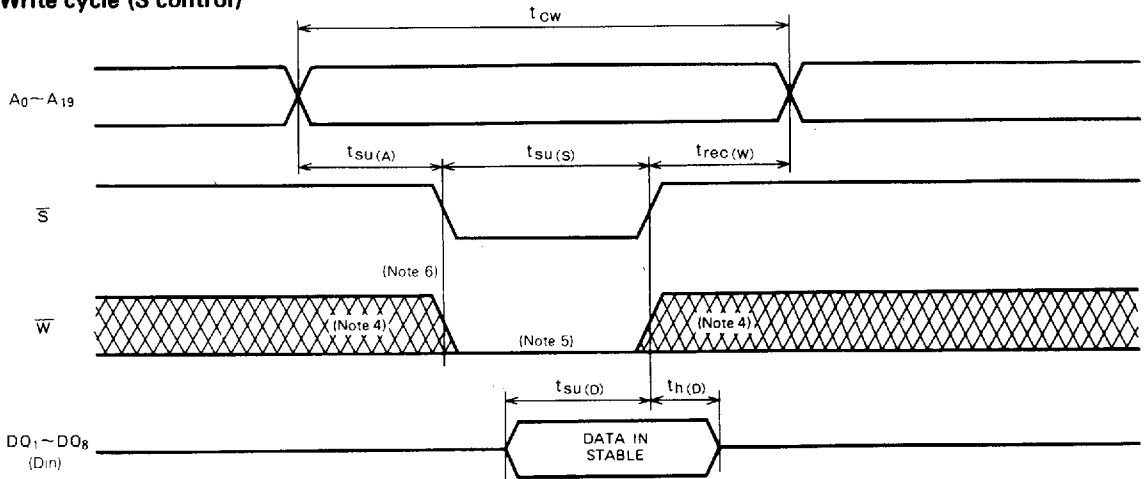


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### Write cycle ( $\bar{S}$ control)



- Note 3 Test condition  
 Input pulse level: 0.6 ~ 2.4V  
 Input pulse rise/fall time: 10ns  
 Load 1 TTL.  $C_L = 100pF$   
 Conditions of assessment, 1.5V
- 4 Hatching indicates the state is don't care.  
 5 Writing is executed in overlap of  $\bar{S}$  and  $\bar{W}$  low.  
 6 If  $\bar{W}$  goes low simultaneously with or prior to  $\bar{S}$ , the output remains in the high, impedance state.  
 7 Don't active inverted phase signal externally when DQ pin is in output mode.

### POWER DOWN CHARACTERISTICS

#### ELECTRICAL CHARACTERISTICS ( $T_a = 0 \sim 70^\circ C$ , unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$V_{CC(PD)}$	Power down supply voltage		2			V
$V_I(\bar{S})$	Chip select input $\bar{S}$	$2.2V \leq V_{CC(PD)}$	3.2			V
		$2V \leq V_{CC(PD)} \leq 2.2V$		$V_{CC(PD)}$		
$I_{CC(PD)}$	Power down supply current	$V_{CC} = 3V, A_{15} \sim A_{19} < 0.2$ or $> V_{CC} - 0.2$ other inputs = $0 \sim V_{CC}$	TNA-L		450	$\mu A$
			TNA-H		130	

### TIMING REQUIREMENTS ( $T_a = 0 \sim 70^\circ C$ , unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$t_{su(PD)}$	Power down setup time		0			ns
$t_{rec(PD)}$	Power down recovery time		5			ms

### POWER DOWN CHARACTERISTICS

